

1.5A, 1000V Fast Avalanche Surface Mount Rectifier

FEATURES

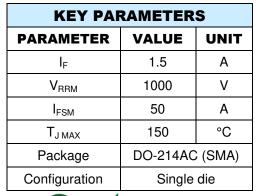
- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

• The superior avalanche capability of BYG21M is specially suited for free-wheeling, clamping, snubber, demagnetization in power supplies and other power switching applications.

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.064g (approximately)







DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)			
PARAMETER	SYMBOL	BYG21M	UNIT
Marking code on the device		BYG21M	
Repetitive peak reverse voltage	V _{RRM}	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	700	V
Forward current	I _F	1.5	Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50	Α
Pulse energy in avalanche mode, non-repetitive (Inductive load switch off), $I_{(BR)R} = 1.23A$	E _{RSM}	30	mJ
Junction temperature	TJ	- 55 to +150	°C
Storage temperature	T _{STG}	- 55 to +150	°C



THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	20	°C/W
Junction-to-ambient thermal resistance	R _{eJA}	70	°C/W

ELECTRICAL SPECIFICAT	(A	,		1	1
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 1.0A, T_J = 25^{\circ}C$	V _F	-	1.5	V
	$I_F = 1.5A, T_J = 25^{\circ}C$		-	1.6	V
Reverse current @ rated $V_{R}^{(2)}$	$T_J = 25^{\circ}C$	I _R	-	1	μA
	$T_J = 100^{\circ}C$		-	10	μA
	T _J = 125°C		-	50	μA
Junction capacitance	1MHz, V _R = 4.0V	CJ	13	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	t _{rr}	-	120	ns

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE	PACKAGE	PACKING
BYG21M	DO-214AC (SMA)	7,500 / Tape & Reel



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

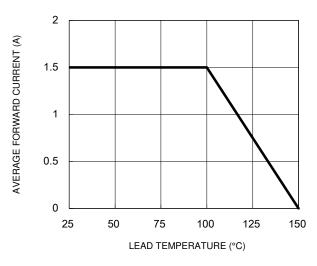


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

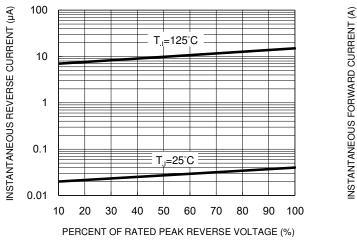
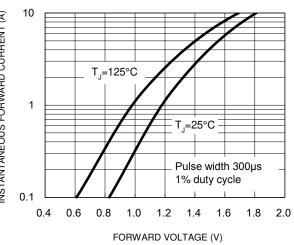
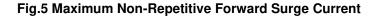
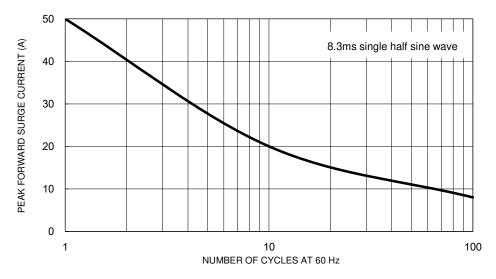


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



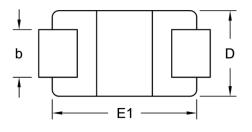


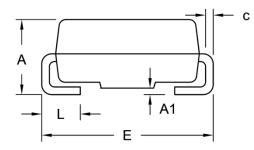


BYG21M Taiwan Semiconductor

PACKAGE OUTLINE DIMENSIONS

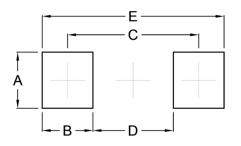
DO-214AC (SMA)





DIM. Unit		(mm)) Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.99	2.50	0.078	0.098
A1	0.10	0.20	0.004	0.008
b	1.27	1.58	0.050	0.062
с	0.15	0.31	0.006	0.012
D	2.29	2.83	0.090	0.111
E	4.95	5.33	0.195	0.210
E1	4.06	4.60	0.160	0.181
L	0.90	1.41	0.035	0.056

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



P/N	= Marking Code

G = Green Compound

YW = Date Code

F = Factory Code



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